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# FDMT800100DC

## N-Channel Dual Cool™ 88 PowerTrench® MOSFET

100 V, 162 A, 2.95 mΩ

### Features

- Max  $r_{DS(on)}$  = 2.95 mΩ at  $V_{GS} = 10$  V,  $I_D = 24$  A
- Max  $r_{DS(on)}$  = 4.46 mΩ at  $V_{GS} = 6$  V,  $I_D = 19$  A
- Advanced Package and Silicon combination for low  $r_{DS(on)}$  and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- Low profile 8x8mm MLP package
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

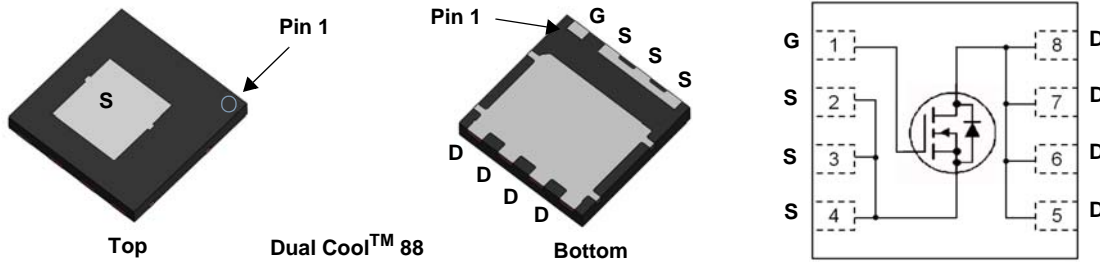


### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process. Advancements in both silicon and Dual Cool™ package technologies have been combined to offer the lowest  $r_{DS(on)}$  while maintaining excellent switching performance by extremely low Junction-to-Ambient thermal resistance.

### Applications

- OringFET / Load Switching
- Synchronous Rectification
- DC-DC Conversion



### MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Rated	Units
$V_{DS}$	Drain to Source Voltage	100	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current -Continuous	$T_C = 25$ °C (Note 5)	162
	-Continuous	$T_C = 100$ °C (Note 5)	102
	-Continuous	$T_A = 25$ °C (Note 1a)	24
	-Pulsed	(Note 4)	989
$E_{AS}$	Single Pulse Avalanche Energy	(Note 3)	1536
$P_D$	Power Dissipation	$T_C = 25$ °C	156
	Power Dissipation	$T_A = 25$ °C (Note 1a)	3.2
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Rated	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Top Source)	1.6	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Bottom Drain)	0.8	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	81	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1i)	15	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1j)	21	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1k)	9	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
800100DC	FDMT800100DC	Dual Cool™ 88	-	13.3 mm	3000 units

FDMT800100DC N-Channel Dual Cool™ 88 PowerTrench® MOSFET

**Electrical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\ \mu\text{A}, V_{GS} = 0\ \text{V}$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		66		mV/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 80\ \text{V}, V_{GS} = 0\ \text{V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\ \text{V}, V_{DS} = 0\ \text{V}$			100	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	2.0	2.8	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		-11		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\ \text{V}, I_D = 24\ \text{A}$		2.3	2.95	m $\Omega$
		$V_{GS} = 6\ \text{V}, I_D = 19\ \text{A}$		3.5	4.46	
		$V_{GS} = 10\ \text{V}, I_D = 24\ \text{A}, T_J = 125\text{ }^\circ\text{C}$		4.2	5.39	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\ \text{V}, I_D = 24\ \text{A}$		66		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 50\ \text{V}, V_{GS} = 0\ \text{V},$ $f = 1\ \text{MHz}$		5595	7835	pF
$C_{oss}$	Output Capacitance			1160	1625	pF
$C_{rss}$	Reverse Transfer Capacitance			39	75	pF
$R_g$	Gate Resistance		0.1	1.4	3.5	$\Omega$

**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50\ \text{V}, I_D = 24\ \text{A},$ $V_{GS} = 10\ \text{V}, R_{GEN} = 6\ \Omega$		29	47	ns	
$t_r$	Rise Time			18	33	ns	
$t_{d(off)}$	Turn-Off Delay Time			40	64	ns	
$t_f$	Fall Time			10	20	ns	
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0\ \text{V to } 10\ \text{V}$		79	111	nC
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0\ \text{V to } 6\ \text{V}$	$V_{DD} = 50\ \text{V},$ $I_D = 24\ \text{A}$	50	70	nC
$Q_{gs}$	Gate to Source Charge			23		nC	
$Q_{gd}$	Gate to Drain "Miller" Charge			16		nC	

**Drain-Source Diode Characteristics**

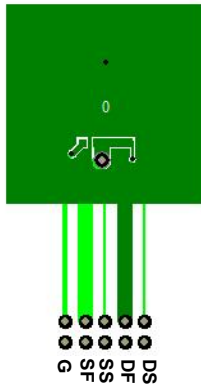
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\ \text{V}, I_S = 2.9\ \text{A}$ (Note 2)		0.7	1.1	V
		$V_{GS} = 0\ \text{V}, I_S = 24\ \text{A}$ (Note 2)		0.8	1.2	
$t_{rr}$	Reverse Recovery Time	$I_F = 24\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}$		71	114	ns
$Q_{rr}$	Reverse Recovery Charge			94	151	nC

## Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Top Source)	1.6	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Bottom Drain)	0.8	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	81	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1c)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1d)	34	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1e)	14	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1f)	16	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1g)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1h)	60	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1i)	15	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1j)	21	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1k)	9	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1l)	11	

### NOTES:

1.  $R_{\theta JA}$  is determined with the device mounted on a FR-4 board using a specified pad of 2 oz copper as shown below.  $R_{\theta CA}$  is determined by the user's board design.



a. 38  $^{\circ}\text{C}/\text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 81  $^{\circ}\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper

- c. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 in<sup>2</sup> pad of 2 oz copper
- d. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
- e. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in<sup>2</sup> pad of 2 oz copper
- f. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
- g. 200FPM Airflow, No Heat Sink, 1 in<sup>2</sup> pad of 2 oz copper
- h. 200FPM Airflow, No Heat Sink, minimum pad of 2 oz copper
- i. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 in<sup>2</sup> pad of 2 oz copper
- j. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
- k. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in<sup>2</sup> pad of 2 oz copper
- l. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty cycle < 2.0%.

3.  $E_{AS}$  of 1536 mJ is based on starting  $T_J = 25^{\circ}\text{C}$ ; N-ch:  $L = 3\text{ mH}$ ,  $I_{AS} = 32\text{ A}$ ,  $V_{DD} = 100\text{ V}$ ,  $V_{GS} = 10\text{ V}$ . 100% test at  $L = 0.1\text{ mH}$ ,  $I_{AS} = 101\text{ A}$ .

4. Pulsed Id please refer to Fig 11 SOA graph for more details.

5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted

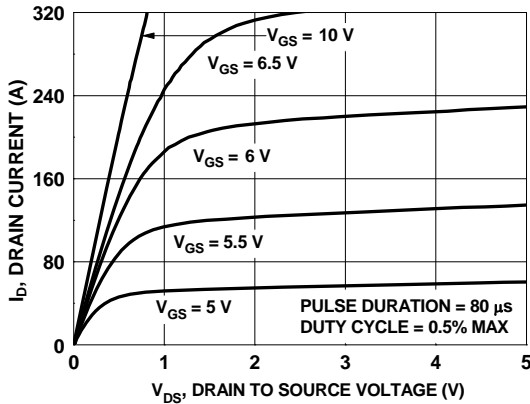


Figure 1. On-Region Characteristics

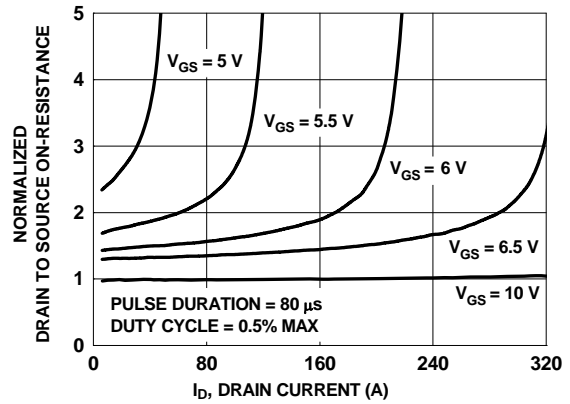


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

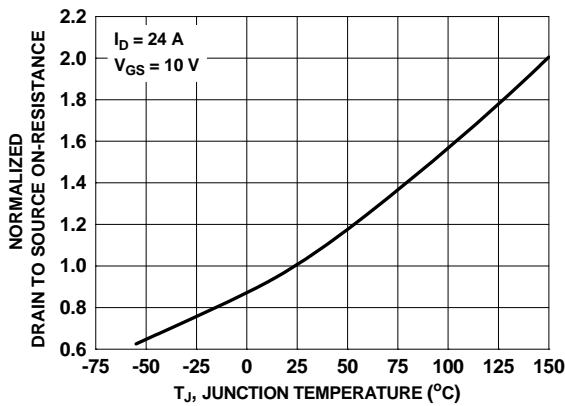


Figure 3. Normalized On-Resistance vs Junction Temperature

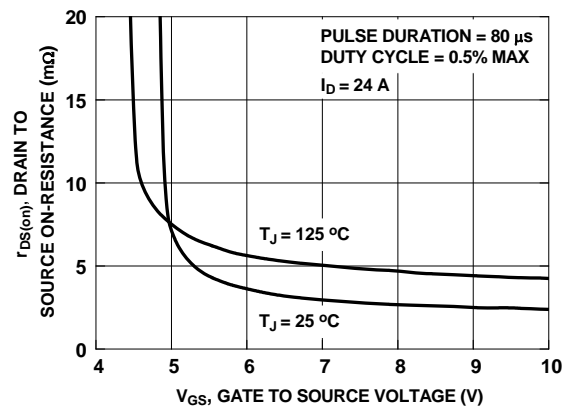


Figure 4. On-Resistance vs Gate to Source Voltage

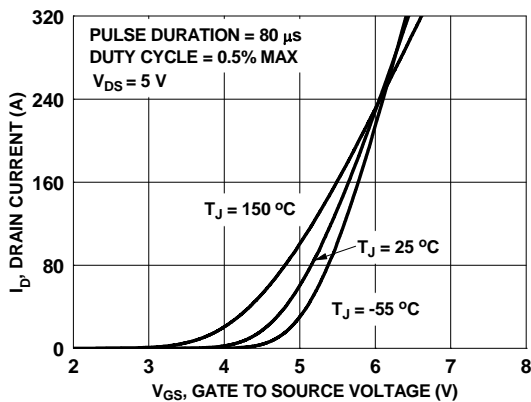


Figure 5. Transfer Characteristics

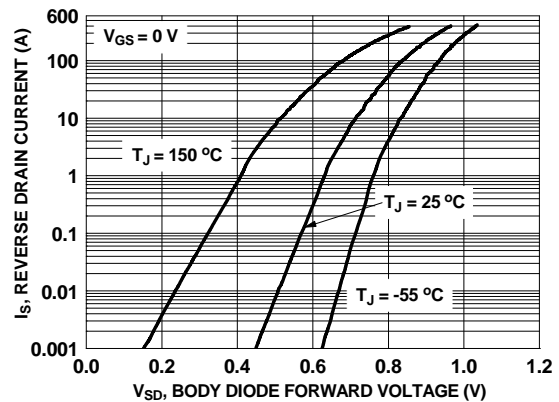
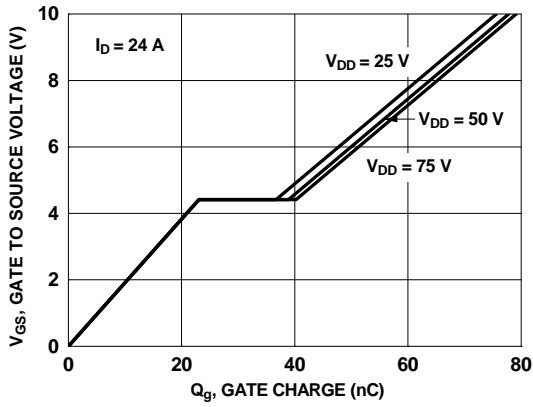
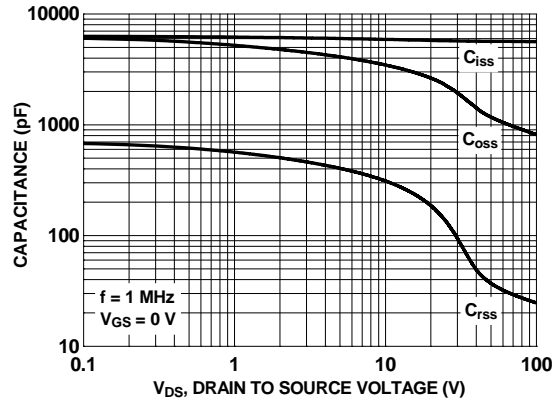


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

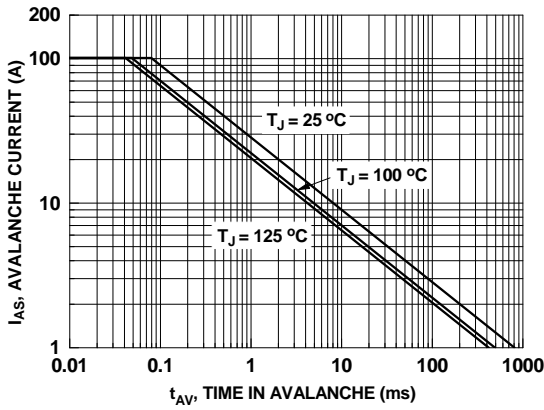
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



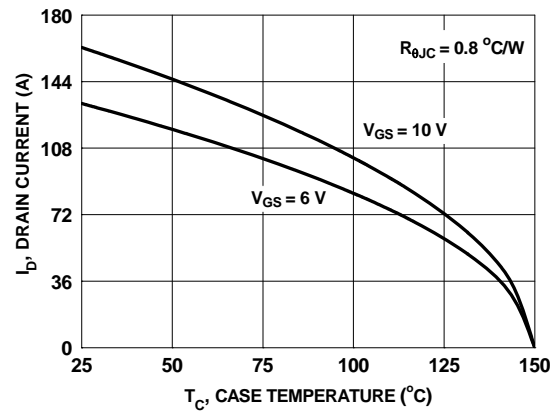
**Figure 7. Gate Charge Characteristics**



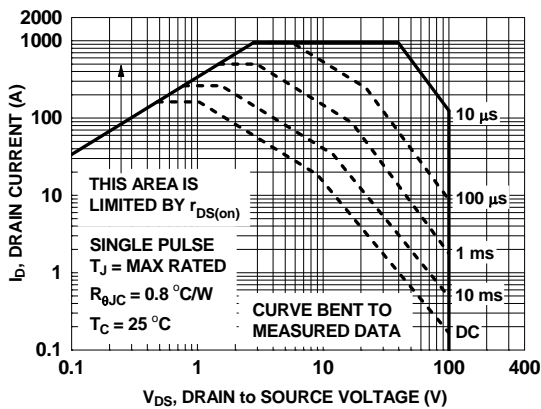
**Figure 8. Capacitance vs Drain to Source Voltage**



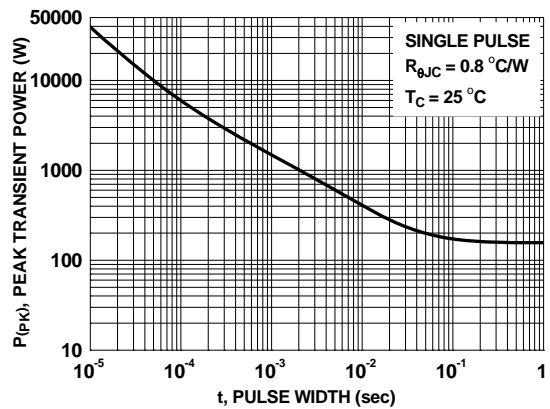
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Maximum Continuous Drain Current vs Case Temperature**

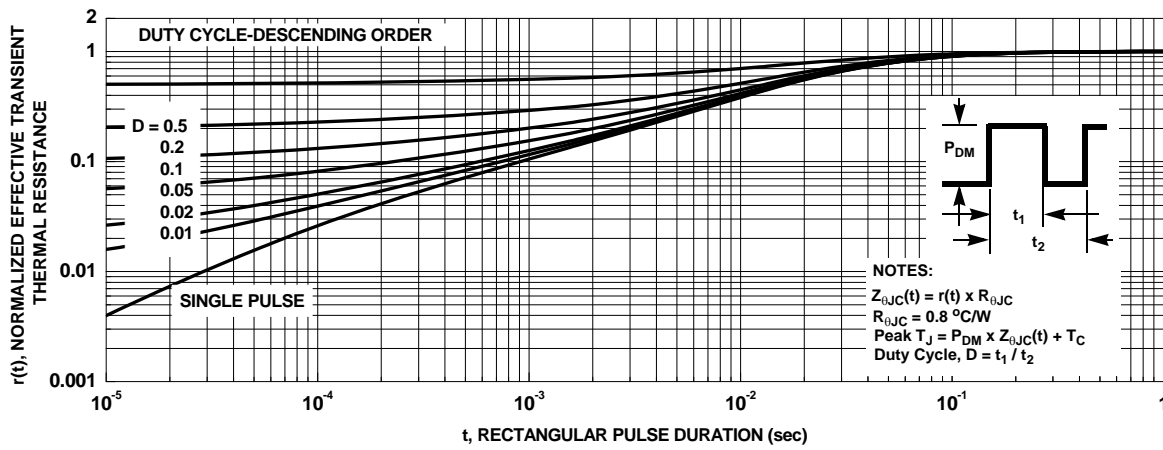


**Figure 11. Forward Bias Safe Operating Area**

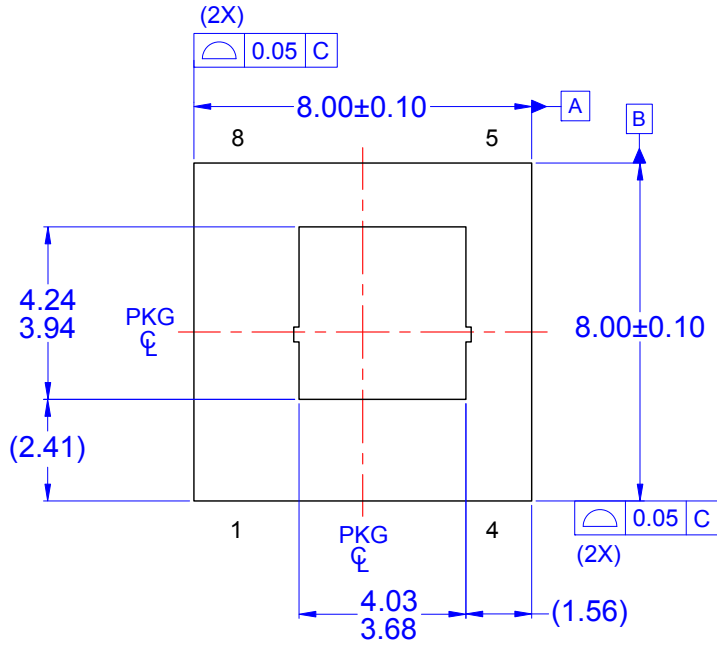


**Figure 12. Single Pulse Maximum Power Dissipation**

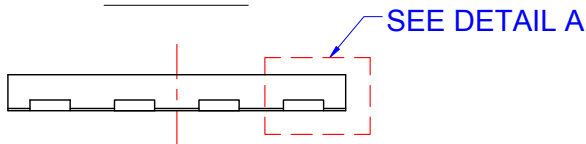
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted



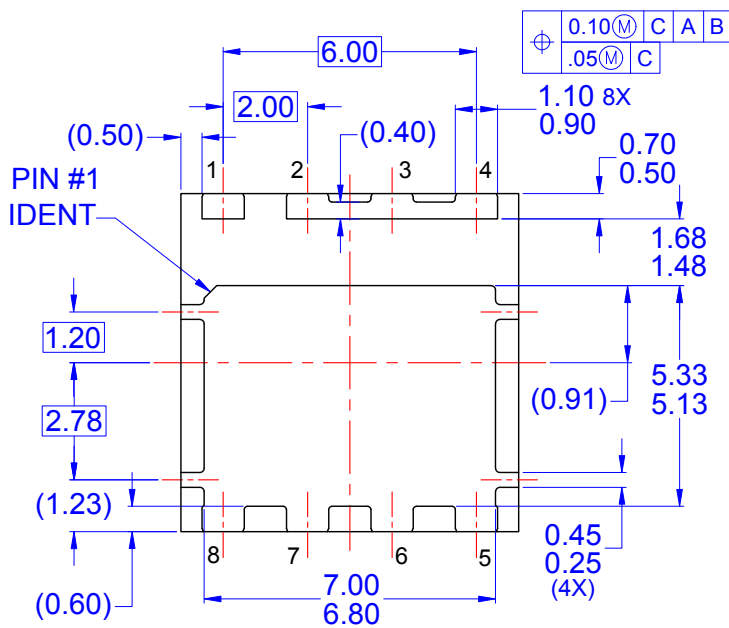
**Figure 13. Junction-to-Case Transient Thermal Response Curve**



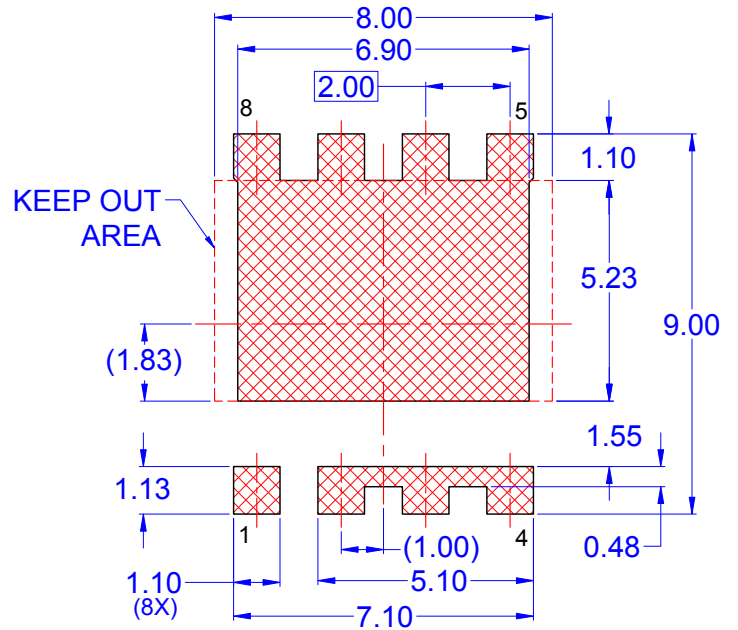
**TOP VIEW**



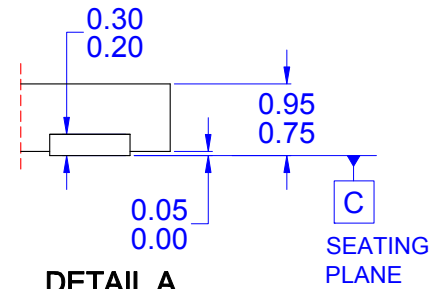
**FRONT VIEW**



**BOTTOM VIEW**



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